

# A 12-bit Column-Parallel Flash TDC-Interpolated Ramp ADC with Online Digital Delay Element Correction

Deyan Levski<sup>1\*</sup>, Martin Wány<sup>2</sup>, Bhaskar Choubey<sup>1</sup>

## Abstract

This work presents a hybrid column-parallel TDC-interpolated Single-Slope ADC which uses a digital feedback to solve the delay element and clock period matching problem in Flash TDC-Interpolation of SS ADCs. The presented feedback correction scheme is applied in-column and occurs online after the end of each conversion, occupying less than 5% of the ramp time at 12-bits. The concept of the architecture is proven on a 1024 × 128 linescan testchip manufactured in a 0.13 μm 1P3M CMOS process, achieving 1 μs ramp time for a 12-bit linear A/D conversion.

<sup>1</sup> Department of Engineering Science, University of Oxford, OX1 3PJ, Oxford, United Kingdom

<sup>2</sup> Austria Microsystems AG, Madeira Tecnopolo, 9020-105, Funchal, Portugal

\*Corresponding author: deyan.levski@eng.ox.ac.uk

## 1. Introduction

The  $2^N$  big-O limiting behavior of Single-Slope (SS) ADCs has led to the exploration of various search space optimization techniques reducing conversion time, while keeping the simplicity and process scalability properties of SS ADCs. A way to increase conversion rate is to perform a coarse quantization in conjunction with a quantization error measurement using a second stage quantizer. This work presents a hybrid column-parallel ADC scheme employing a coarse-fine SS architecture from the Nutt-interpolation family [1].

## 2. Proposed Flash TDC-Interpolation with Digital Delay Element Correction

The concept of Flash TDC interpolation is presented on Fig. 1. A count clock incrementing an SS ADC counter is fed through a chain of delay elements, providing an  $N$  number of clock taps, phase shifted by time  $\tau$ . During an A/D comparator toggle event the state of the main and delayed clocks are latched. Each additional clock tap adds one quantization step whose value, after thermometer to binary code conversion, is directly concatenated as an LSB word to the MSB word of the main binary SS counter. Direct word concatenation in TDC-interpolated SS ADCs can be successful only if both the SS counter and interpolating TDC yield a radix-2 output word. Thus, for the general case of a Flash TDC interpolating a DDR SS counter, the total sum of the delay line must equal  $1/2$  the clock period  $T$ . In order to maintain DNL of  $<0.5$  LSB, the delayed clocks must be designed such that the cumulative deviation of the sum of all delays is less than  $\pm 1/2 \tau_{dly}$ , as well as their matching in-between. The design of fixed analog delay elements, which maintain stable delay time within PVT corners is challenging, if not impossible, without the use of some form of referenced feedback, which is the case of the previously presented DLL-based scheme in [2]. The current work uses a digital feedback and solves the delay element and clock period matching problem by employing TDC code redundancy with a follow-up TDC code retraction back to radix-2, owing to an online in-column calibration operation. Fig. 2 shows a high-level overview of the proposed scheme, which, to achieve a target goal

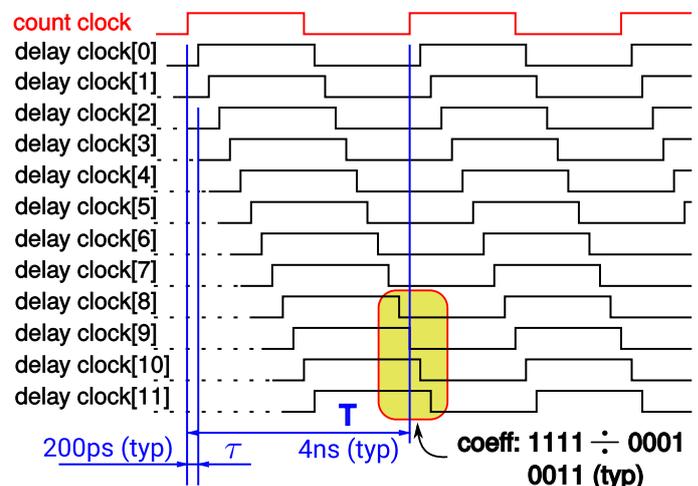


Figure 1. Principle of the proposed Flash TDC-Interpolated SS ADC

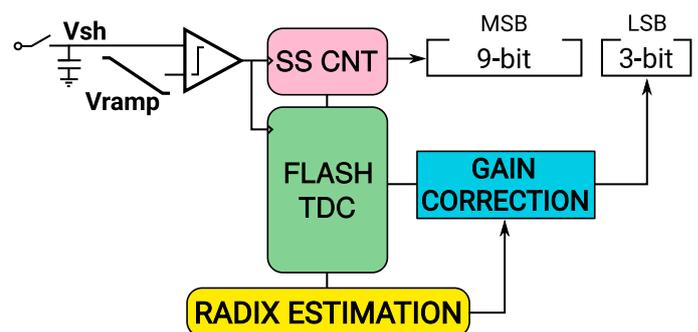


Figure 2. System-level overview of the interpolation scheme

of 1 μs conversion time at 12-bits, uses a 3-bit TDC interpoating a 9-bit DDR SS counter at 250 MHz. The interpolating TDC is formed by eight primary clock phases plus four additional clocks which introduce the redundancy and lower the TDC radix varying from 1.45 to 1.8. The delays are designed such that under all PVT corners yield an overlap with the main count clock edge within the limits of “1111” - “0001”, as shown on Fig. 1, with a typical targeted overlap value of “0011” (radix 1.55), so as to maximize the room for delay drift with PVT corners in both directions.



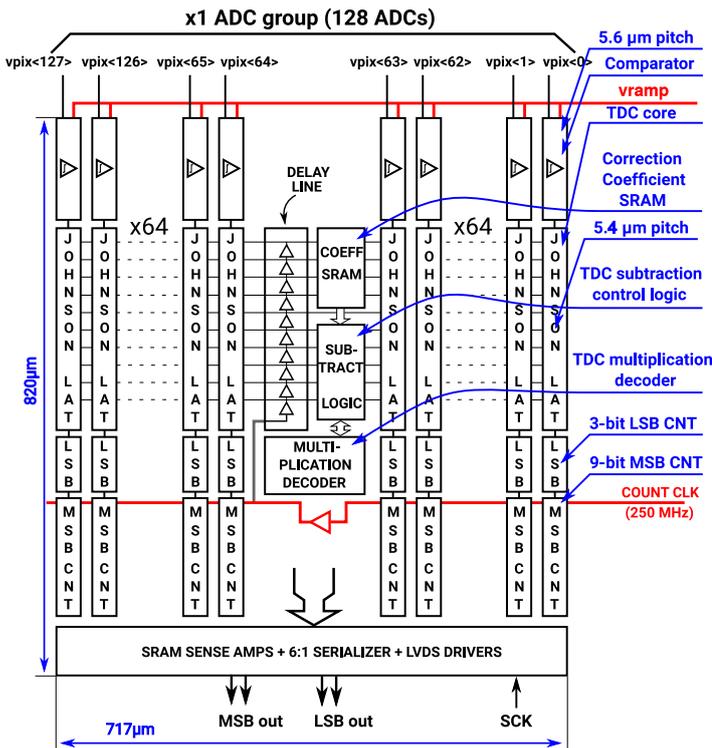


Figure 5. ADC group physical diagram

subtracted TDC words from SHR and SHS sampling result in an underflow. The latter is executed by the BOROUT block, which ensures a borrow out propagation link between the LSB and MSB counters. Fig. 4b displays a simplified timing procedure of a single DCDS conversion. Each column features dual swappable sample and hold capacitors which allows for a fully pipelined mode of operation. During the count period the digital sequencer introduces 255 count clock cycles, while at the same time the ramp reference is slewed. At the time point when the input sample and ramp cross, the comparator toggles, freezing the MSB counter and TDC latch content. When *count\_en* is disabled, the conversion operation is finished and the last correction coefficient acquired during the conversion phase is stored into the coefficient storage memory *coeff[3:0]* by the *strobe\_coeff\_en* signal. After the MSB count phase, the LSB counter is enabled with *count\_lsb\_en*, while the sequencer issues twelve count clocks on *count\_clk* which drive the ring skip counter. The latter addresses each TDC latch consecutively, while skipping latches depending on the state of the *sw\_disable* signal, issued by the multiplication decoder and controlled by the stored correction coefficient and algorithm on Fig. 3. To perform DCDS the values of both counters are inverted, followed by a second A/D conversion operation of SHS. Finally the counter state is transferred to a shadow SRAM for readout via per-group 2 × 6:1 serialization blocks and LVDS Tx.

#### 4. ADC Characterization Results

A 1024 column x 128 line testchip was manufactured in 0.13 µm 1P3M CIS process. Table I provides the characterized ADC performance at 1 µs ramp time mode. The latter implies a count clock of 250 MHz, which imposes a typical Flash TDC delay unit time of 200 ps, thus, being ≈ 6× the intrinsic gate propagation delay in the used process. Fig. 6 and 7 show the INL and DNL of a single column (mid-array column 512), although the linearity

Parameter	This Work
Process	0.13 µm 1P3M FSI CIS
Array Size	1024 (H) × 128 (V) RGBW
Pixel Pitch / Height	5.6 µm / 820 µm
Resolution	12-bit
Row Time (incl. DCDS)	4.4 µs
Ramp Time	1 µs
Counting Scheme	Flash TDC-Interpolated
ADC Count Clock Frequency	250 MHz
INL	+5.8/-8.2 LSB
DNL	+1.1/-0.4 LSB
Input Range	1.5 – 2.9 V (341 µV/LSB)
Noise Stdev. at 1x gain (LSB)	477 µV (1.48 LSB)
CFPN (at >3000 DN)	≈ 0.15 %
Data Output	16 LVDS ports at 250 Mbps
Power (incl. refs, excl. LVDS)	177 µW/column
Temperature Range	-20 – 70 °C
Power Supply	1.5 V (dig), 3.3 V (ana)

performance is well matched within all columns. The observed DNL glitches occur at the interpolation point between the MSB and LSB counter (every 16th count) which are due to unfortunate design-influenced propagation delay difference in the TDC latch elements (L0–L10) and the DDR latch zero (LM0) of the MSB counter. Partial degradation of the count clock duty cycle by the LVDS clock receiver also contributes to the observed non-linearity peak at the interpolation point codes. The latter should be taken care of and can be easily eliminated with the use of an accurate on-chip PLL and careful latch optimization. The DNL floor below 0.5 LSB is primarily due to the numerical noise introduced by the fixed point multiplication (truncation of numerical residue for radix correction), which is architecture-inherited. The INL measurement is likely to be influenced by the dynamic histogram test measurement setup and finite settling of the S/H circuitry which filter and distort the pure sinewave test signal. Fig. 8 shows the total output ADC noise of a full DCDS conversion at 1x, 2x and 4x gain, which is achieved through ramp slope modulation. The input range of the ADC at 1x gain spans between 1.5 – 2.9 V (1.4 V abs) with an LSB of 341 µV, yielding an input-referred noise of 477 µV RMS at 1x gain. Fig. 8d shows the mean column output with an identical input test voltage to all 1024 columns averaged over 30 K samples. The worst case column fixed pattern noise normalized over full scale (4096) is 0.11-0.15 % which is influenced by a slight inefficiency of the comparator kickback noise compensation scheme affecting the ramp reference line. The latter is generated via a global constant-current discharge of local (per-column) 100 fF MIM capacitors. The calibration coefficient capture is within the designed recoverable range. Group-to-group correction coefficient matching spans between ±1 digital code and does not induce a noticeable group-to-group offset. Tests under uniform (DAC-provided) and random (pixel-provided) input voltage confirm that load-induced calibration coefficient drift is insignificant, owing to a strong digital power supply network and locally distributed decoupling. Fig. 9 shows the floorplan of the device, which employs eight individual ADC groups of x128 columns, each possessing dual 6:1 serialization channels and 250 Mbps Sub-LVDS drivers. Fig. 10 and Fig. 11 show images of the top-level chip layout and test board.

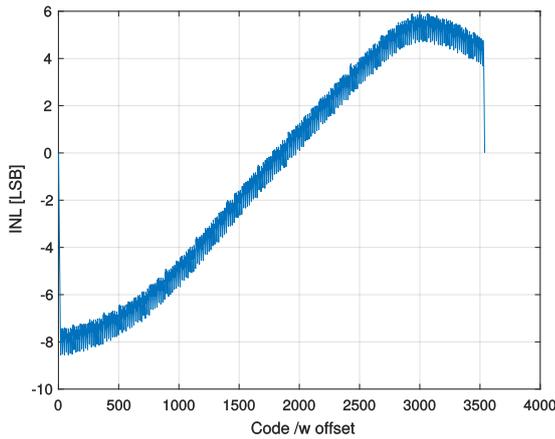


Figure 6. Integral Nonlinearity

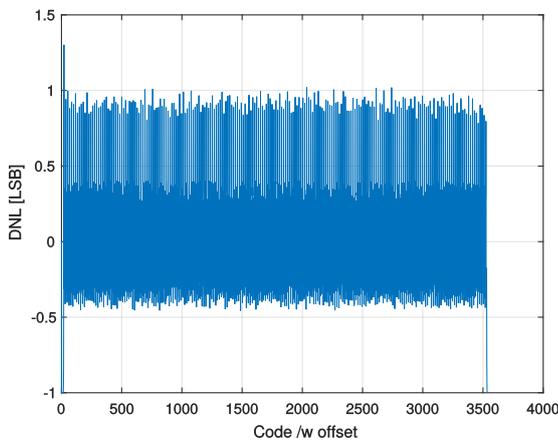


Figure 7. Differential Nonlinearity

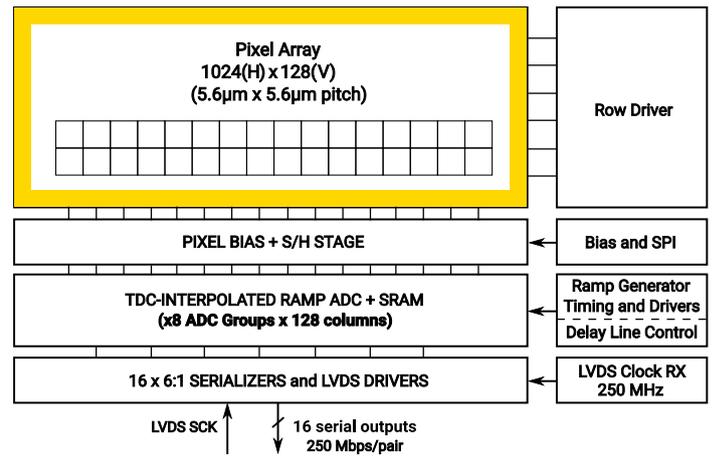


Figure 9. ADC testchip floorplan

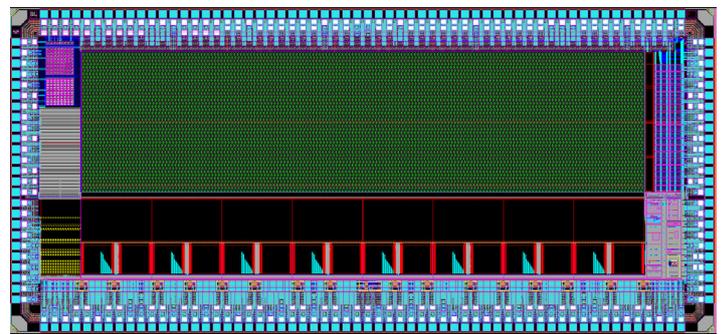


Figure 10. Top-level overview



Figure 11. Outlook of the test system

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## References

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